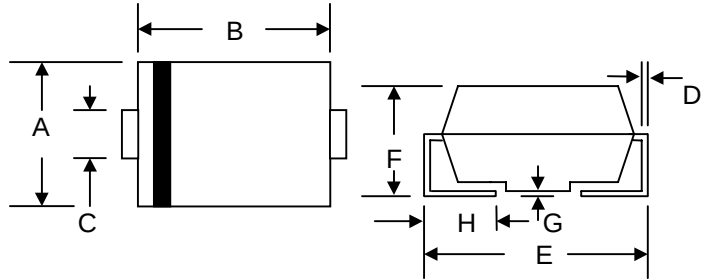




Features

- Schottky Barrier Chip
- Ideally Suited for Automatic Assembly
- Low Power Loss, High Efficiency
- Surge Overload Rating to 30A Peak
- For Use in Low Voltage Application
- Guard Ring Die Construction
- Plastic Case Material has UL Flammability Classification Rating 94V-O



Mechanical Data

- Case: SMA/DO-214AC, Molded Plastic
- Terminals: Solder Plated, Solderable per MIL-STD-750, Method 2026
- Polarity: Cathode Band or Cathode Notch
- Marking: Type Number
- Weight: 0.064 grams (approx.)
- **Lead Free: For RoHS / Lead Free Version, Add "-LF" Suffix to Part Number, See Page 4**

SMA/DO-214AC		
Dim	Min	Max
A	2.50	2.90
B	4.00	4.60
C	1.20	1.60
D	0.152	0.305
E	4.80	5.28
F	2.00	2.44
G	0.051	0.203
H	0.76	1.52
All Dimensions in mm		

Maximum Ratings and Electrical Characteristics @T_A=25°C unless otherwise specified

Characteristic	Symbol	SS12	SS13	SS14	SS15	SS16	SS18	SS19	S100	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	20	30	40	50	60	80	90	100	V
RMS Reverse Voltage	V _{R(RMS)}	14	21	28	35	42	56	64	71	V
Average Rectified Output Current @T _L = 75°C	I _O	1.0								A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}	30								A
Forward Voltage @I _F = 1.0A	V _{FM}	0.50			0.70		0.85			V
Peak Reverse Current @T _A = 25°C At Rated DC Blocking Voltage @T _A = 100°C	I _{RM}	0.5 20								mA
Typical Thermal Resistance (Note 1)	R _{θJL} R _{θJA}	28 88								°C/W
Operating Temperature Range	T _j	-65 to +125								°C
Storage Temperature Range	T _{STG}	-65 to +150								°C

Note: 1. Mounted on P.C. Board with 5.0mm² copper pad area.

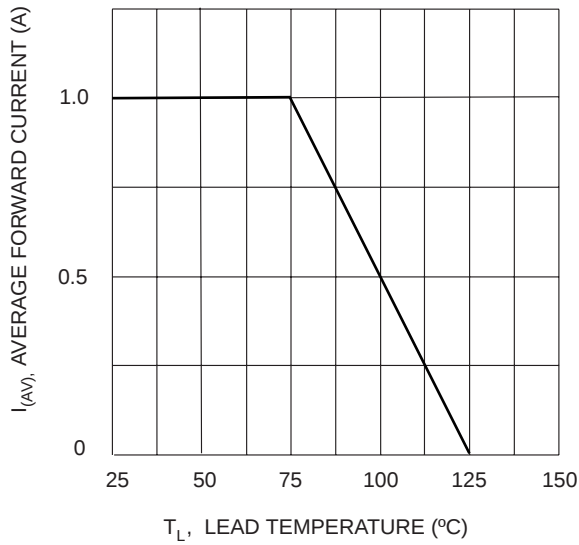


Fig. 1 Forward Current Derating Curve

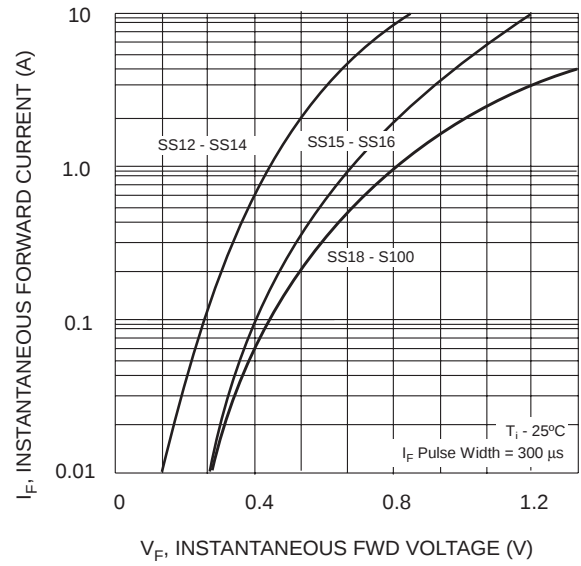


Fig. 2 Typ. Forward Characteristics

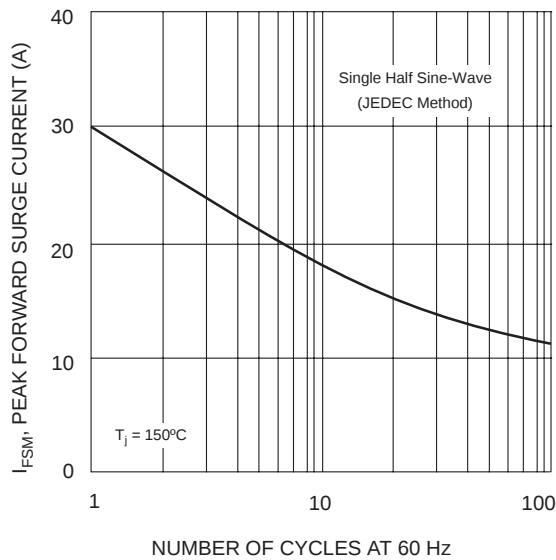


Fig. 3 Max Non-Repetitive Peak Fwd Surge Current

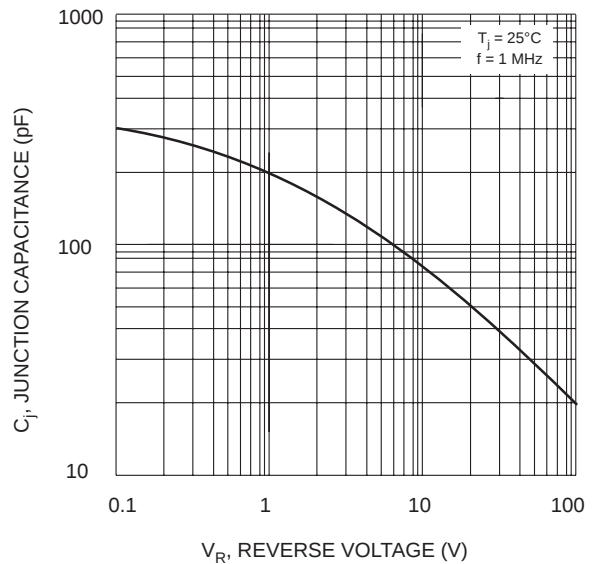


Fig. 4 Typical Junction Capacitance

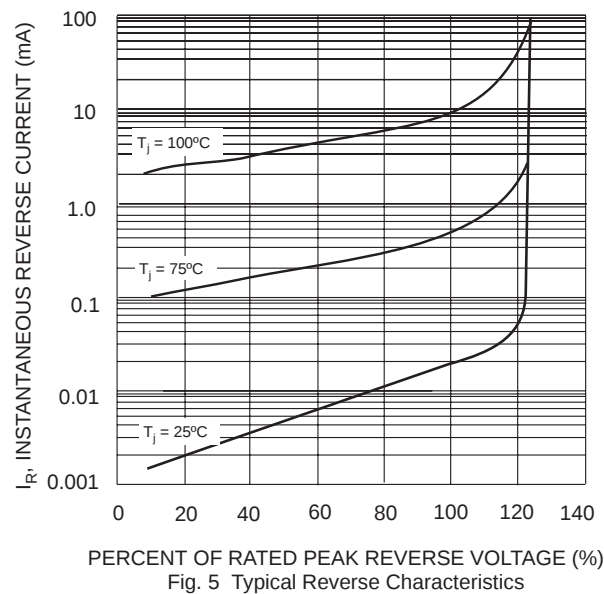


Fig. 5 Typical Reverse Characteristics